

LQP40-LX4

QSFP+ 40Gbps LX4 2km(SMF)@150m(MMF@OM3) DDM Transceiver

PRODUCT FEATURES

- Supports 41.2 Gb/s aggregate bit rates
- Uncooled 4x10Gb/s transmitter
- Maximum link length of 2km on Single Mode Fiber (SMF)
And 150m on OM3(MMF)
- Hot-pluggable QSFP+ footprint
- Duplex LC receptacles
- Power dissipation<3.5W
- RoHS-6 compliant and lead-free
- Single 3.3V power supply
- Support Digital Diagnostic Monitor interface
- Case operating temperature
Commercial: 0°C to +70°C

APPLICATIONS

- 40GBASE-LX4 Ethernet

COMPLIANCE

- QSFP+ MSA
- SFF-8436
- IEEE802.3ba
- RoHS

PRODUCT DESCRIPTION

LQP40-LX4 QSFP+ transceiver modules are designed for use in 40 Gigabit Ethernet links over single-mode fiber and multi-mode fiber. They are compliant with the QSFP+ MSA and IEEE 802.3ba 40GBASE-LX4. Module-level digital diagnostic functions are available via an I²C interface, as specified by the QSFP+ MSA. The optical transceiver is compliant per the RoHS Directive 2011/65/EU.

Ordering Information

Package	Product part NO.	Data Rate (Gbps)	Media	Wavelength (nm)	Transmission Distance(km)	Temperature Range (°C)	
QSFP+	LQP40-LX4	41.2	single-mode fiber	1271nm, 1291nm	2	0~70	Commercial
			multi-mode fiber	1311nm, 1331nm	0.15(OM3)		

I. Absolute Maximum Ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Ref.
Storage Temperature	T _s	-40		85	°C	
Storage Ambient Humidity	H _A	5		95	%	
Maximum Supply Voltage	V _{cc1} , V _{ccTx} , V _{ccRx}	-0.5		3.6	V	
Signal Input Voltage		-0.3		V _{cc} +0.3	V	
Receiver Damage Threshold		+3.4			dBm	
Lead Soldering Temperature/Time	TSOLD			260/10	°C/sec	1
Lead Soldering Temperature/Time	TSOLD			360/10	°C/sec	2

Notes:

1. Suitable for wave soldering.
2. Only for soldering by iron.

II. General Product Characteristics

Parameter	Value	Unit	Ref.
Module Form Factor	QSFP+		

Number of Lanes	4 Tx and 4 Rx		
Maximum Aggregate Data Rate	41.2	Gb/s	
Maximum Data Rate per Lane	10.3125	Gb/s	Higher bit rates may be supported. Please contact Lightrend
Protocols Supported	Typical applications include 40G Ethernet		
Management Interface	Serial, I2c-based, 400kHz maximum frequency		As defined by the QSFP+ MSA

Data Rate Specifications	Symbol	Min.	Typ.	Max.	Unit	Ref.
Bit Rate per Lane	BR			10313	Mb/s	1
Bit Error Ratio	BER			10^{-12}		2
Link distance on SMF/MMF	d			2; 0.15(OM3)	km	

Notes:

1. Compliant with 40GBASE-LX4 and XLPP1 per IEEE 802.3ba. Compatible with 1/10 Gigabit Ethernet and 1/2/4/8/10G Fiber Channel.
2. Tested with a PRBS 231-1 test pattern.

III. Optical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Ref.
Transmitter						
Total Average Launch Power for SMF	P_{OUT}			8.3	dBm	
Total Average Launch Power for MMF				9.5	dBm	
Average Output Power per lane for SMF	P_{ave}	-7.0		2.3	dBm	
Average Output Power per lane for MMF		-5.0		3.5	dBm	
Transmit OMA per Lane for SMF	TxOMA	-6.0		3.5	dBm	
Transmit OMA per Lane for MMF		-4.0		4.5	dBm	
Extinction Ratio	ER	3.5			dB	
Center Wavelength	λ_C	1264.5 1284.5 1304.5 1324.5	1271 1291 1311 1331	1277.5 1297.5 1317.5 1337.5	nm	
Sidemode Suppression ratio	SMSR	30			dB	

Transmitter and Dispersion Penalty	TDP			2.6	dB	
Transmitter OFF Output Power	POff			-30	dBm	
Transmitter eye mask definition {X1, X2, X3, Y1, Y2, Y3}		0.25,0.4,0.45,0.25,0.28,0.4				
Receiver						
Input Optical Wavelength	λ_{IN}	1264.5	1271	1277.5	nm	
		1284.5	1291	1297.5		
		1304.5	1311	1317.5		
		1324.5	1331	1337.5		
Rx Sensitivity (OMA) per lane for SMF	R _{SENS1}			-11.5	dBm	
Rx Sensitivity (OMA) per lane for MMF				-10.5	dBm	
Stressed Rx Sensitivity (OMA) per lane	R _{SENS2}			-9.6	dBm	
Input Saturation Power (Overload) for SMF	PSAT			+2.3	dBm	
Input Saturation Power (Overload) for MMF				+3.5		
Receiver Reflectance	R _{fl}			-26	dBm	
Loss of Signal Assert	P _A	-30			dBm	
Loss of Signal De-assert	P _D			-12.5	dBm	
LOS Hysteresis	P _D - P _A	0.5		6	dB	

IV. Electrical Interface Characteristics

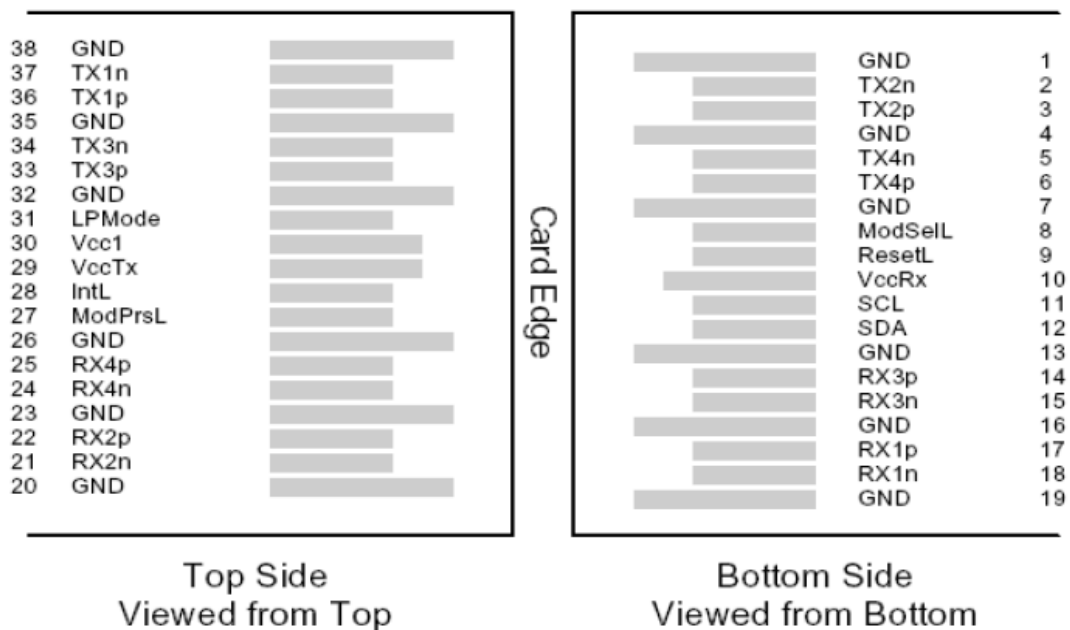
Parameter	Symbol	Min.	Typ.	Max.	Unit	Ref.
Supply Voltage	V _{CC1} , V _{CCTx} , V _{CCRx}	3.15		3.45	V	
Supply Current	I _{CC}			1000	mA	
Transmitter						
Input different impedance	R _{in}	90	100	110	Ω	2
Single ended data input swing	V _{in} , pp	120		820	mV	
Transmitter Disable Voltage	V _{DIS}	2		V _{CC}	V	3
Transmitter Enable Voltage	V _{EN}	0		0.8	V	
Receiver						
Output different impedance	R _{out}	90	100	110	Ω	2
Single ended data output swing	V _{out} , pp	340		850	mV	4

LOS Asserted	V _{LOSA}	2		V _{CCHOST}	V	5
LOS De-asserted	V _{LOSD}	0		0.8	V	5
Power Supply Rejection	PSR	50			mVpp	

Notes:

1. Maximum total power value is specified across the full temperature and voltage range.
2. Connected directly to TX data input pins. AC coupled thereafter.
3. Or open circuit.
4. Into 100Ω differential termination.
5. LossOf Signal is LVTTTL. Logic “0” indicates normal operation; logic “1” indicates no signal detected.

V. Pin Diagram



QSFP+ MSA-compliant 38-pin connector

VI. Pin Descriptions

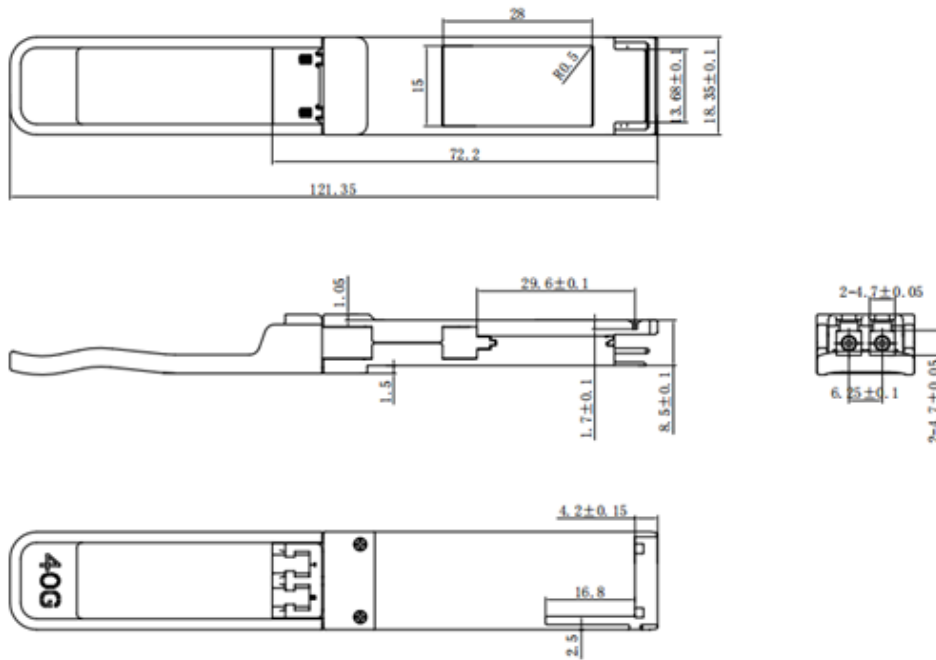
Pin	Symbol	Name/Description	Ref.
1	GND	Ground	1
2	Tx2n	Transmitter Inverted Data Input	
3	Tx2p	Transmitter Non-Inverted Data Input	
4	GND	Ground	1
5	Tx4n	Transmitter Inverted Data Input	
6	Tx4p	Transmitter Non-Inverted Data Input	
7	GND	Ground	1
8	ModSe1L	Module Select	

9	ResetL	Module Reset	
10	Vcc Rx	+3.3V Power supply receiver	
11	SCL	2-wire serial interface clock	
12	SDA	2-wire serial interface data	
13	GND	Ground	1
14	Rx3p	Receiver Non-Inverted Data Output	
15	Rx3n	Receiver Inverted Data Output	
16	GND	Ground	1
17	Rx1p	Receiver Non-Inverted Data Output	
18	Rx1n	Receiver Inverted Data Output	
19	GND	Ground	1
20	GND	Ground	1
21	Rx2n	Receiver Inverted Data Output	
22	Rx2p	Receiver Non-Inverted Data Output	
23	GND	Ground	1
24	Rx4n	Receiver Inverted Data Output	
25	Rx4p	Receiver Non-Inverted Data Output	
26	GND	Ground	1
27	ModPrSL	Module Present	
28	IntL	Interrupt	
29	VccTx	+3.3V Power supply transmitter	
30	Vcc1	+3.3V Power Supply	
31	LPMode	Low Power Mode	
32	GND	Ground	1
33	Tx3p	Transmitter Non-Inverted Data Input	
34	Tx3n	Transmitter Inverted Data Input	
35	GND	Ground	1
Pin	Symbol	Name/Description	Ref.
36	Tx1p	Transmitter Non-Inverted Data Input	
37	Tx1n	Transmitter Inverted Data Input	
38	GND	Ground	1

Note:

1. Circuit ground is internally isolated from chassis ground.

VII. Mechanical Specifications(Unit: mm)



Revision History

Version No.	Date	Description
1.0	June 24, 2021	Preliminary datasheet